Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"425"/$.ccls. and (injection with (mold or mould)) and (silicon with insert)	US-PGPUB; USPAT	OR	ON	2004/12/10 16:45
L2	5	(injection with (mold or mould)).ti. and (silicon with insert)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:03
L3	1	(injection with (mold or mould)).ti. and (silicon) and (microstructures or microreplication)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 16:48
L4	823	(425/190).CCLS.	US-PGPUB; USPAT	OR	OFF	2004/12/10 16:49
L5	270	4 and (injection with (mold or mould))	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 16:49
L6	15	("2621369" | "2651810" | "2976571" | "3781402" | "3810599" | "3951580" | "4422986" | "4479914" | "4666323" | "4712936" | "4797236").PN. OR ("5531582"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:03
L7	1	(injection with (mold or mould) with (microreplication or microstructures)).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:08
L8	25	(injection with (mold or mould) with (micro)).ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:06
L9	0	("2002098611").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:06
L10	1	("20020098611").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:06
L11	149	(injection with (mold or mould)) same (micro-device or microfabricated or microneedle)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/10 17:10
L12	1	("5,512,131").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:10

L13	141	("2905539" | "4587213" | "4690715" | "5032216" | "5079600" | "5143854" | "5202227" | "5259926").PN. OR ("5512131").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:10
L14	12	("4614630" | "5250023" | "5304487" | "5498392" | "5879326" | "5885470").PN. OR ("6331266").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:21
L15	24	("4614630").URPN.	USPAT	OR	ON	2004/12/10 17:29
L16	6	"4307869"	EPO; DERWENT	OR	ON	2004/12/10 17:31
L17	5	"437345"	EPO; DERWENT	OR	ON	2004/12/10 17:31
L18	3	"9748440"	EPO; DERWENT	OR	ON	2004/12/10 17:33
L19	1	"5234571"	EPO; DERWENT	OR	ON	2004/12/10 17:33
L20	1	("5234571").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:33
L21	15	("5234571").URPN.	USPAT	OR	ON	2004/12/10 17:44
L22	1	("5645977").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/10 17:44
L23	13	("5234571" | "5298366").PN. OR ("5645977").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/10 17:44
S1	6	"1088642"	EPO; DERWENT	OR	ON	2004/12/08 16:57
S2	25	silicon and molds	IBM_TDB	OR	ON	2004/12/08 12:14
S3	6	"4307869"	EPO; DERWENT	OR	ON	2004/12/08 12:28
S4	1	1994-286599.NRAN.	DERWENT	OR	ON	2004/12/08 12:15
S6	55	("425"/$.ccls. or "249"/$.ccls. or "264"/$.ccls.) and (micron or submicron).ti.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 12:57
S7	561	(425/810).CCLS.	US-PGPUB; USPAT	OR	OFF	2004/12/08 12:34
S8	6	S7 and (silicon with stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 17:46
S9	8	S7 and (silicon same stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 12:36
S10	2	((optical with (disk or disc)) and mold).ti. and (silicon with stamper)	EPO; JPO; DERWENT	OR	ON	2004/12/08 12:38

S11	0	((optical with (disk or disc)) and mold).ti. and (silicon with stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 12:38
S13	17	((optical with (disk or disc)) and mold) and (silicon with stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 12:42
S14	3	"0437345"	EPO; DERWENT	OR	ON	2004/12/08 12:42
S15	5	"437345"	EPO; DERWENT	OR	ON	2004/12/08 12:44
S16	9	"74764"	EPO; DERWENT	OR	ON	2004/12/08 12:49
S17	0	(injection with (mold or mould)).ti. and microreplication	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 12:50
S18	28	(injection with (mold or mould)) and microreplication	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 12:50
S19	13	("0086660" | "20020035854" | "20030102591" | "3399425" | "3822857" | "4208368" | "4846938" | "5077870" | "5688193" | "5845375" | "6223401").PN. OR ("6824378"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 12:54
S20	31	("425"/$.ccls. or "249"/$.ccls. or "264"/$.ccls.) and microreplication	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 13:00
S21	1	("5772905").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 13:00
S22	45	("3743842" | "4310743" | "4325779" | "4383026" | "4450358" | "4498009" | "4516253" | "4552615" | "4576678" | "4606788" | "4731155" | "4832790" | "5277749").PN. OR ("5772905"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 13:06
S23	1	("5501784").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 13:06
S24	14	("4661212" | "5055163" | "5234571").PN. OR ("5501784"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/08 13:12
S25	1	("5234571").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 13:12

S26	15	("5234571").URPN.	USPAT	OR	ON	2004/12/08 13:13
S29	313	"425"/$.ccls. and (injection adj (mold or mould)) and (insert with cavity)	USPAT	OR	ON	2004/12/08 16:59
S30	561	(425/810).CCLS.	US-PGPUB; USPAT	OR	OFF	2004/12/08 17:46
S31	8	S30 and (silicon same stamper)	US-PGPUB; USPAT	OR	ON	2004/12/08 17:46
S32	19	"425"/$.ccls. and (injection with (mold or mould)) and (silicon with (bond or bonded or adhesive))	US-PGPUB; USPAT	OR	ON	2004/12/10 16:42
S33	244	(mold or mould) and (silicon with cavity) and (microstructures or microreplication)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/08 17:54
S34	1	("5,110,514").PN.	US-PGPUB; USPAT	OR	OFF	2004/12/08 17:54